

# **DIP316-001BLF**

### **DIP316-001BLF Information**

Heisener.com	 DIP316-001BLF Amphenol FCI Connectors, Interconnects Sockets for ICs, Transistors CONN IC DIP SOCKET 16POS GOLD - For the pricing/inventory/lead time, please contact	
For Reference Only	us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

# **Certified Quality**

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



# **DIP316-001BLF** Specifications

ManufacturerAmphenol FCICategoryConnectors, InterconnectsSockets for ICs, TransistorsPackage-Series-SpriesDIP, 0.3" (7.62mm) Row SpacingNumber of Positions or Pins (Grid)16 (2 x 8)Pitch - MatingOilo0" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating3ujui (0.76µm)Contact Finish Thickness - MatingBeryllium CopperContact Material - MatingGoleMounting TypeThrough HoleFeaturesOpen FramePitch - Post0.100" (2.54mm)Contact Finish Thickness - MatingSolderContact Material - MatingGoleContact Material - MatingGoleContact Material - MatingGolerContact Finish Thickness - MatingGolerContact Finish Thickness - MatingGolerContact Material - MatingGolerContact Material - MatingGolerContact Finish Thickness - MatingGolerContact Finish Thickness - MatingGolerContact Finish - NostGolerContact Finish - PostGolupin (5.58µm)Contact Finish - PostGolupin (5.58µm)Contact Finish Thickness - PostGolupin (5.08µm)Contact Material - PostGrassHousing MaterialPolycyclonexylenedimethylene Terephthalate (PCT), Polysetser, Glass Filled	-	
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Contact Material - PostBrassHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), Polyester, Glass FilledOperating Temperature-	Contact Finish - Post	Tin
Housing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), Polyester, Glass FilledOperating Temperature-	Contact Finish Thickness - Post	200µin (5.08µm)
Operating Temperature -	Contact Material - Post	Brass
	Housing Material	Polycyclohexylenedimethylene Terephthalate (PCT), Polyester, Glass Filled
Report errors?	Operating Temperature	-
		Report errors?

#### **DIP316-001BLF Guarantees**



Quality Guarantees

We provide 90 days warranty. \* If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

# SERVICE BUARANTEE

#### **Service Guarantees**

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

#### **DIP316-001BLF Payment Methods**



## **DIP316-001BLF Shipping Methods**



If you have any question about DIP316-001BLF, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com